

10007304
12/05/01

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10007304	FILING DATE 12/05/2001	CLASS 438	SUBCLASS 629	GAU 2812	EXAMINER FAHMY
----------------------	---------------------------	--------------	-----------------	-------------	-------------------

**APPLICANTS: Kim Ki-Bum; Soininen Pekka; Raaijmakers Ivo;

285

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 10-2000-0074025 12/06/2000

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO ASMMC.033AUS
TITLE : Copper interconnect structure having stuffed diffusion barrier			

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner			
Primary Examiner		DRAWING	
PREPARED F R ISSUE		Sheets Drwg.	Figs. Drwg.
Application Examiner		Print Fig.	
TERMINAL DISCLAIMER			
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

DISK (CRF)

CD-ROM
(Attached in pocket on right inside flap)